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PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Bi-Ming YEN	12/05/2012
Tsai-Chun LI	12/05/2012
Chun-Ming HU	12/05/2012

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	No. 8, Li-Hsin Rd. VI, Hsinchu Science Park
City:	Hsinchu
State/Country:	TAIWAN
Postal Code:	300

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13714756

CORRESPONDENCE DATA

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NAME OF SUBMITTER: Randy A. Noranbrock

Total Attachments: 1

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PATENT REEL: 029470 FRAME: 0203 OP \$40.00 13714756

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Docket No. T5057-804 TSMC2012-0767

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- 1) Bi-Ming YEN
- 2) Tsai-Chun LI
- Chun-Ming HU

who has made a certain new and useful invention, hereby sells, assigns and transfers unto TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD., having a place of business at No. 8, Li-Hsin Rd, VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

METHOD OF MAKING A SEMICONDUCTOR DEVICE USING MULTIPLE LAYER SETS

(a)	for which an application for United States Letters Patent was filed on $\frac{2012-12-14}{}$, and identified by United States Patent Application No. $\frac{13/714}{,756}$; or
(b)	for which an application for United States Letters Patent was executed on,
all Unite	undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and add States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or this international thereof, and the right to all benefits under the International Convention for the Protection of Industrial

agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to

Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned

SIGNED on the date indicated aside my signature:

the invention hereby transferred.

RECORDED: 12/14/2012

PATENT REEL: 029470 FRAME: 0204